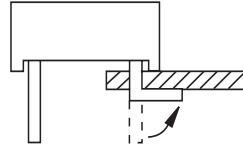


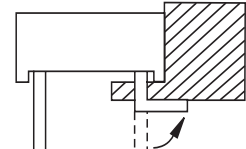
The Following Precautions must be taken to protect the reliability of Displays.

(1) FORMING:

- a.** Please don't form the DISPLAY after soldering. If forming is necessary, it must be done before soldering.
- b.** Any unsuitable stress applied to the epoxy body may break bonding wires in DISPLAY.



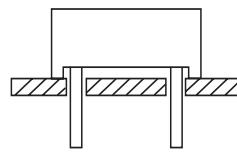
(Correct)



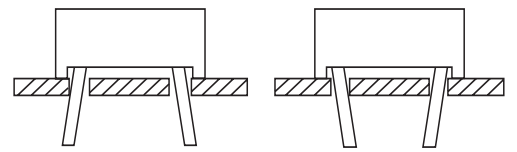
(Wrong)

(2) INSTALLATION:

- a.** Do not apply physical stress to the PINS when mounting led displays on PCB.
- b.** Installation with holder - The holder should be designed not to subject pins to any stress.



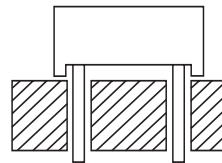
(Correct)



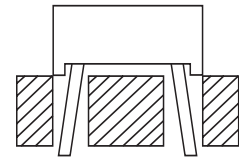
(Wrong)

(3) SOLDERING:

- a.** Do not dip epoxy body into solder bath.
- b.** Do not apply stress to pins while they are heated.
- c.** Acceptable soldering condition.



(Correct)



(Wrong)

KINDS OF SOLDERING		CONDITIONS
SOLDER IRON		300° C ± 5° C, WITHIN 3 SECONDS (1.6mm FROM SEATING PLANE)
SOLDER BATH		260° C ± 5° C, WITHIN 5 SECONDS (1.6mm FROM SEATING PLANE)
REFLOW SOLDERING	PRE HEATING	75° C ± 5° C, WITHIN 30 SECONDS
	SOLDERING	245° C ± 5° C, WITHIN 5 SECONDS (1.6mm FROM SEATING PLANE)

(4) CLEANING:

- a.** In any case, the dipping or steam cleaning time should be one (1) minute or less, a normal temperature.
- b.** When cleaning is required, please refer to the following table.

ACCEPTABLE SOLVENT	FORBIDDEN SOLVENT
Alcohol	thinner, acetone, freon tmc, diflon S3MC, trichloroethylene, chlorosen.

- c.** Do not clean leds with water as the remains may rust the leads.
- d.** Leds may be damaged in an ultrasonic cleaning process. A sample led should be cleaned prior to mass cleaning to assure integrity.